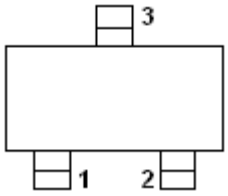
1. Description

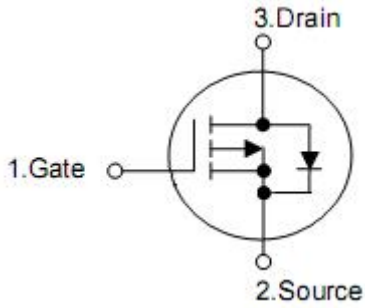
The KIA3423 uses advanced trench technology to provide excellent $R_{DS(on)}$,low gate charge and operation with gate voltages as low as 2.5V.This device is suitable for use as a load switch or in PWM applications.Standard Product KIA3423 is Pb-free(meets ROHS & Sony 259 specifications).KIA3423 is a Green Product ordering option.KIA3423 is electrically identical.

2. Features

- V_{DS}(V)=-20V
- I_D=-2.0A
- $R_{DS(on)}$<92mΩ(V_{GS}=-10V,I_D=-2.0A)
- $R_{DS(on)}$<118mΩ(V_{GS}=-4.5V,I_D=-2.0A)
- $R_{DS(on)}$<166mΩ(V_{GS}=-2.5V,I_D=-1.0A)

3.Symbol





Pin	Function
1	Gate
2	Source
3	Drain

4. Absolute maximum ratings

(T_A=25°C,unless otherwise noted)

Parameter		Symbol	Rating	Units
Drain-source voltage		V_{DS}	-20	V
Gate-source voltage		V_{GS}	±12	V
Continuous drain current [A]	T_A=25ºC[F]	I_D	-2.0	A
	T_A=70ºC[F]		-2.0	
Pulsed drain current [B]		I_{DM}	-8	A
Total power dissipation [A]	T_A=25 ºC	P_D	1.4	W
	T_A=70ºC		0.9	W
Junction and storage temperature range		T_J,T_{STG}	-55 to150	ºC

5. Thermal characteristics

Parameter	Symbol	Typ	Max	Unit
Maximum junction-ambient [A](t≤10s)	$R_{\theta JA}$	65	90	ºC/W
Maximum junction-ambient [A]	$R_{\theta JA}$	85	125	ºC/W
Maximum junction-Lead [C]	$R_{\theta JL}$	43	60	ºC/W

6. Electrical characteristics

(T_A=25°C,unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Drain-source breakdown voltage	BV_{DSS}	V_{GS}=0V,I_D=-250μA	-20	-	-	V
Zero gate voltage drain current	I_{DSS}	V_{DS}=-16V, V_{GS}=0V	-	-	-0.5	μA
Gate- body leakage current	I_{GSS}	V_{GS}=±10V, V_{DS}=0V	-	-	±1	μA
		V_{GS}=±12V, V_{DS}=0V	-	-	±10	
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=-250μA	-0.7	-0.9	-1.4	V
On state drain current	$I_{D(on)}$	V_{GS}=-4.5V, V_{DS}=-5V	-8	-	-	A
Static drain-source on-resistance	$R_{DS(on)}$	V_{GS}=-10V,I_D=-2.0A	-	76	92	mΩ
		V_{GS}=-4.5V,I_D=-2.0A	-	94	118	
		V_{GS}=-2.5V,I_D=-1.0A	-	128	166	
Forward transconductance	gfs	V_{DS}=-5.0V, I_D=-2A	-	6.8	-	S
Diode forward voltage	V_{SD}	V_{GS}=0V,I_S=-1A	-1	-0.78	-	V
Maximum body-diode continuous current	I_S		-	-	-1.8	A
Input capacitance	C_{iss}	V_{DS}=-10V,V_{GS}=0V, f=1MHz	-	512	620	pF
Output capacitance	C_{oss}		-	77	-	
Reverse transfer capacitance	C_{rss}		-	62	-	
Gate resistance	R_g	V_{DS}=0V, V_{GS}=0V,f=1MHz	-	9.2	13	Ω
Total gate charge	Q_g	V_{DS}=-10V, V_{GS}=-4.5V I_D =-2.0A	-	5.5	6.6	nC
Gate-source charge	Q_{gs}		-	0.8	-	
Gate-drain charge	Q_{gd}		-	1.9	-	
Turn-on delay time	$t_{d(on)}$	V_{DS}=-10V, R_L=5Ω,, R_G=3Ω, V_{GS}=-10V	-	5	-	ns
Rise time	t_r		-	6.7	-	
Turn-off delay time	$t_{d(off)}$		-	28	-	
Fall time	t_f		-	13.5	-	
Reverse recovery time	t_{rr}	IF=-2A,dI/dt=100A/μs,	-	9.8	12	nS
Reverse recovery charge	Q_{rr}		-	2.7	-	nC

Note:A.The value of $R_{\theta JA}$ is measured with the device mounted on 1 in^2 FR-4 board with 2oz.Copper,in a still air environment with T_A=25℃.The value in any given application depends on the user's specific board design.The current rating is based on the t≤10s thermal resistance rating.

B.Repetitive rating,pulse width limited by junction temperature.

C.The $R_{\theta JA}$ the sum of the thermal inpedence from junction to lead $R_{\Theta jl}$ and lead to ambient.

D.The static characteristics in Figures 1 to 6,12,14 are obtained using 80μs pulses,duty cycle 0.5% max.

E.These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper,in a still air environment with T_A=25℃.The SOA curve provides a single pulse rating.

F.The maximum current rating is limited by bond-wires.

7. Test circuits and waveforms

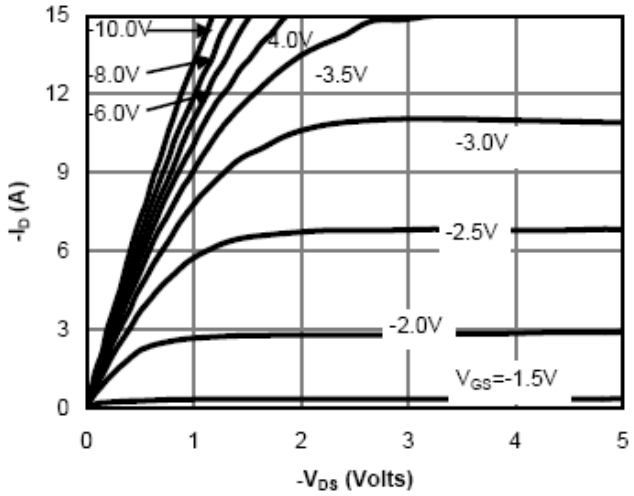


Fig 1: On-Region Characteristics

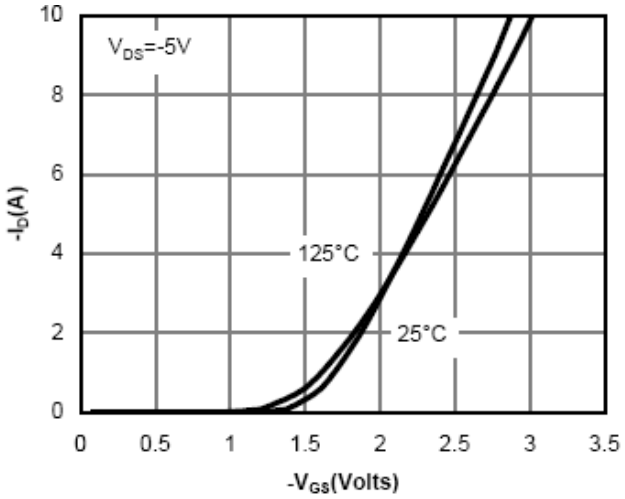


Figure 2: Transfer Characteristics

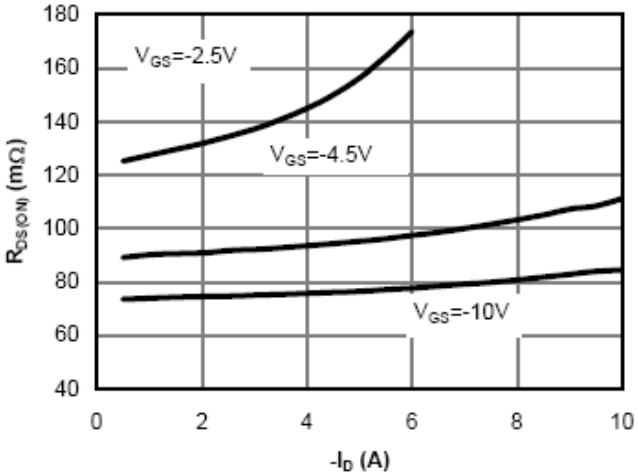


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

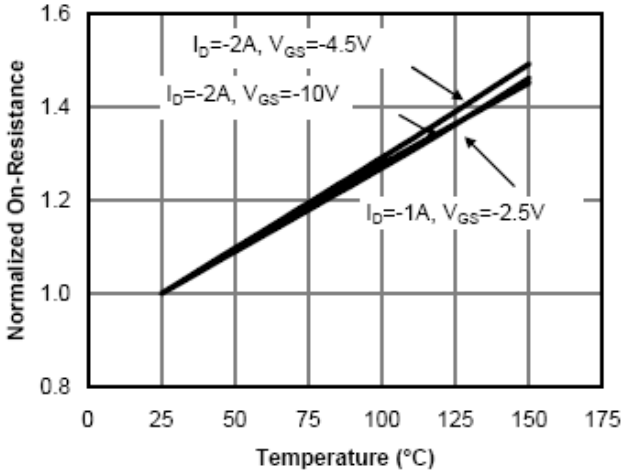


Figure 4: On-Resistance vs. Junction Temperature

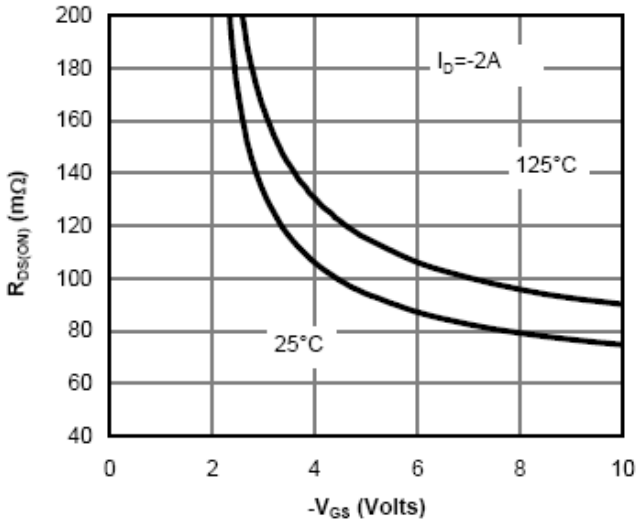


Figure 5: On-Resistance vs. Gate-Source Voltage

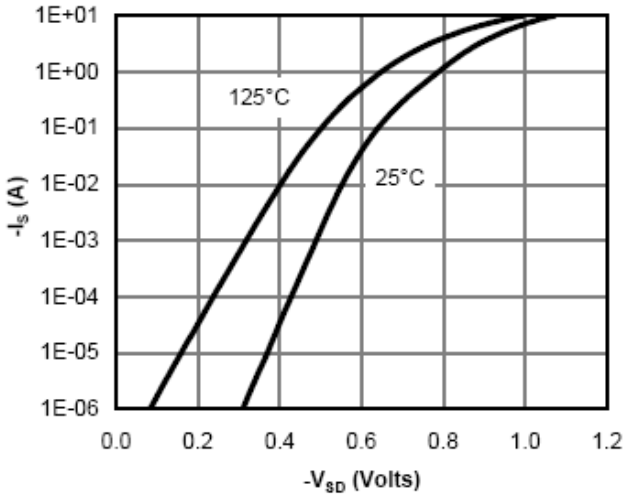


Figure 6: Body-Diode Characteristics

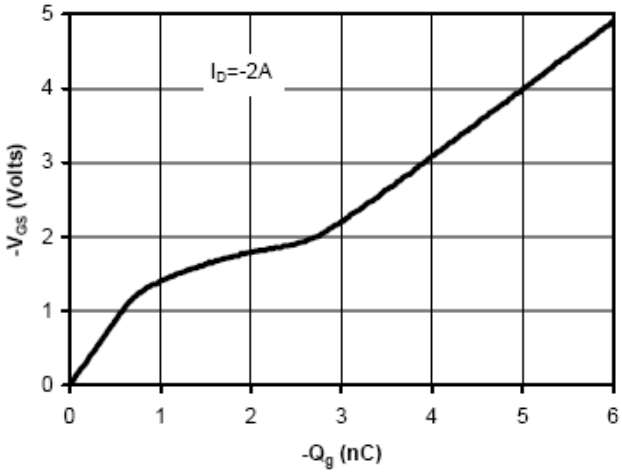


Figure 7: Gate-Charge Characteristics

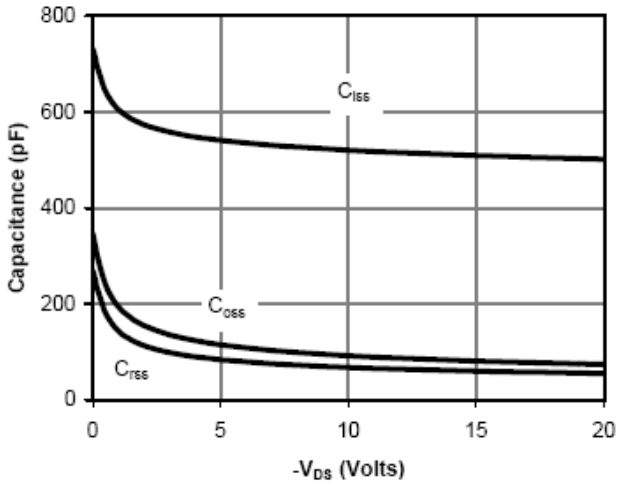


Figure 8: Capacitance Characteristics

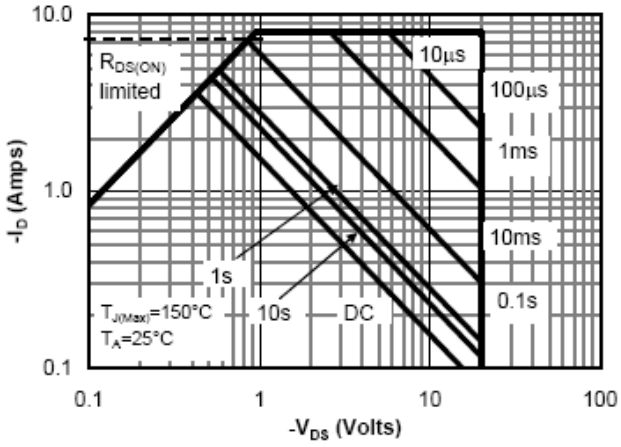


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

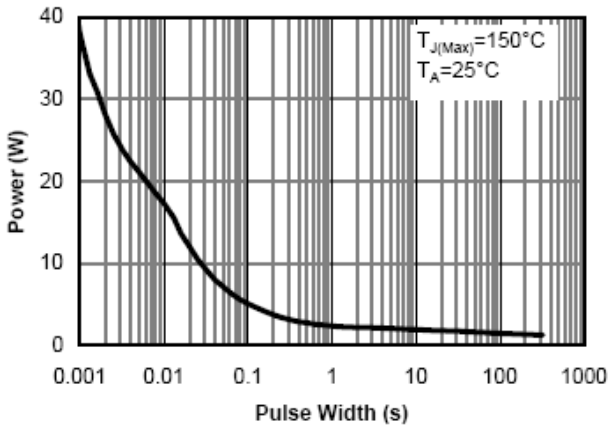


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

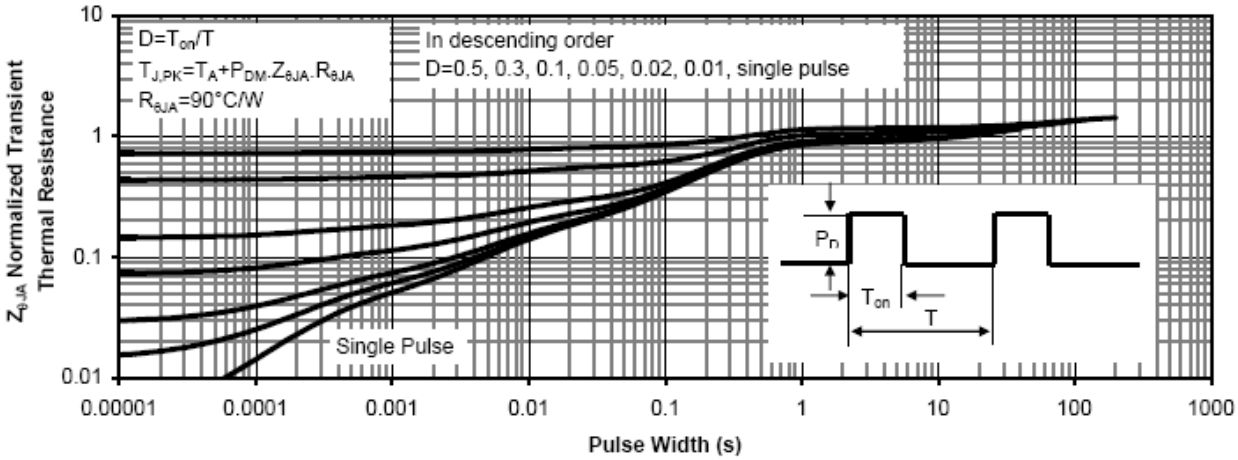


Figure 11: Normalized Maximum Transient Thermal Impedance